



Material Content Data Sheet



Sales Product Name		ICE3AR10080CJZ		Issued		24. January 2018			
MA#		MA001729112							
Package		PG-DIP-7-3		Weight*		645.10 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.854	0.60	0.60	5974	5974	
leadframe	inorganic material	phosphorus	7723-14-0	0.048	0.01		75		
	non noble metal	zinc	7440-66-6	0.194	0.03		300		
	non noble metal	iron	7439-89-6	3.872	0.60		6002		
wire	non noble metal	copper	7440-50-8	157.218	24.37	25.01	243710	250087	
	noble metal	gold	7440-57-5	0.394	0.06	0.06	610	610	
	encapsulation	organic material	carbon black	1333-86-4	2.348	0.36		3639	
encapsulation	plastics	epoxy resin	-	63.390	9.83		98263		
	inorganic material	silicondioxide	60676-86-0	403.817	62.60	72.79	625974	727876	
leadfinish	non noble metal	tin	7440-31-5	6.460	1.00	1.00	10013	10013	
plating	noble metal	silver	7440-22-4	1.594	0.25	0.25	2471	2471	
glue	plastics	epoxy resin	-	0.335	0.05		520		
	noble metal	silver	7440-22-4	1.580	0.24	0.29	2449	2969	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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